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Kerry Veenstra, Bruce Pedersen, Jay Schleicher, Chiakang Sung

March 1998 **Proceedings of the 1998 ACM/SIGDA sixth international symposium on Field programmable gate arrays**Full text available: [pdf\(557.16 KB\)](#) Additional Information: [full citation](#), [abstract](#), [references](#), [citations](#), [index terms](#)

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Jin H. Kim, Daniel P. Siewiorek

 June 1980 **Proceedings of the 17th conference on Design automation**

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With the exponential explosion in chip complexity there is a growing need for high level design aids. A preliminary experiment was conducted in mating a hierarchical, top-down DA system for data paths with an existing IC placement and router. Nine designs ranging in complexity from 7 to 150 register transfers were synthesized. Strong correlations were observed between high level, abstract measures and final placed and routed chip area. It was observed that use of logic primitives of a moder ...

2 [Optimizations for a highly cost-efficient programmable logic architecture](#)

Kerry Veenstra, Bruce Pedersen, Jay Schleicher, Chiakang Sung

 March 1998 **Proceedings of the 1998 ACM/SIGDA sixth international symposium on Field programmable gate arrays**

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Gabet, R.; Bondiou, M.; Stephan, G.; Besnard, P.;

Lasers and Electro-Optics, 1999. CLEO '99. Summaries of Papers Presented at the Conference

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2. Coherent operation of monolithically integrated master oscillator amplifiers

Welch, D.F.; Mehuys, D.; Parke, R.; Waarts, R.; Scifres, D.; Streifer, W.;

Electronics Letters

Volume 26, Issue 17, 16 Aug. 1990 Page(s):1327 - 1329

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Marazita, S.M.; Bishop, W.L.; Hesler, J.L.; Hui, K.; Bowen, W.E.; Crowe, T.W.;

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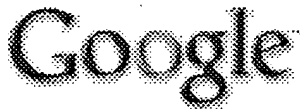
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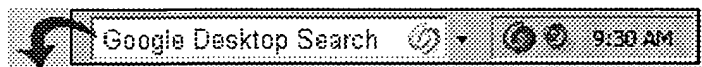
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